

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Yasushi TOKUMO et al.

Application No.: 09/625,047

Filed: July 24, 2000

For: TEST SOCKET, METHOD OF
MANUFACTURING THE TEST
SOCKET, TEST METHOD USING THE
TEST SOCKET, AND MEMBER TO BE
TESTED



Group Art Unit: 2858

Examiner: Unassigned

INFORMATION DISCLOSURE STATEMENT
TRANSMITTAL LETTER

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Enclosed is an Information Disclosure Statement and accompanying form PTO-1449 for the above-identified patent application.

- ☒ No additional fee for submission of an IDS is required.
- ☐ The fee of \$180.00 (126) as set forth in 37 C.F.R. § 1.17(p) is also enclosed.
- ☐ A certification under 37 C.F.R. § 1.97(e) is also enclosed.
- ☐ A certification under 37 C.F.R. § 1.97(e), a petition requesting consideration of the information disclosure statement, and the petition fee of \$130.00 (122) as set forth in 37 C.F.R. § 1.17(i) are also enclosed.
- ☐ Charge \$_____ to Deposit Account No. 02-4800 for the fee due.
- ☐ A check in the amount of \$_____ is enclosed for the fee due.

The Commissioner is hereby authorized to charge any appropriate fees under 37 C.F.R. §§ 1.16, 1.17 and 1.21 that may be required by this paper, and to credit any overpayment, to Deposit Account No. 02-4800. This paper is submitted in duplicate.

Respectfully submitted,

BURNS, DOANE, SWECKER & MATHIS, L.L.P.

By:

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Date: November 17, 2000

5/IDS
E. J. J. J. J.
1-10-01

Patent
Attorney's Docket No. 019519-259

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

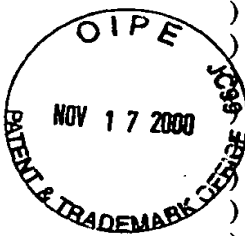
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INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In accordance with the duty of disclosure as set forth in 37 C.F.R. § 1.56, Applicants hereby submit the following information in conformance with 37 C.F.R. §§ 1.97 and 1.98.

Pursuant to 37 C.F.R. § 1.98, a copy of each of the documents cited is enclosed.

1. JP 58-199545
2. JP 5-94856
3. JP 10-228969
4. JP 5-104856
5. JP 4-34380
6. U.S. Application No. 09/480,945
(No copy is provided since we do not have access to this reference.)

Attached is a copy of Applicants' comments regarding references 1 through 5.

The documents are being submitted within 3 months of the filing or entry of the national stage of this application or before the first Office Action on the merits, whichever is later, therefore no fee or certification is required under 37 C.F.R. § 1.97(b).

To assist the Examiner, the documents are listed on the attached form PTO-1449. It is respectfully requested that an Examiner initialed copy of this form be returned to the undersigned.

Respectfully submitted,

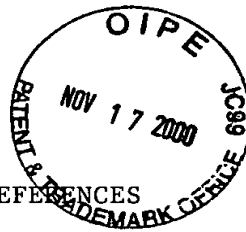
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APPLICANTS' COMMENTS REGARDING CITED REFERENCES

1. Japanese Patent Unexamined Publication No, Sho 58-199545:

Description is given of this publication in the specification of the invention.

2. Japanese Patent Unexamined Publication No., Hei 5-94856:

This publication discloses:

a contact is formed in rink shaped; and
since relative sliding movement is suppressed, formation of an agglomerated solder is a little.

The shape of the contact is similar to the invention. However, since concave and convex portion is not formed at an end of the contact, it is difficult for this publication to obtain good electrical contact.

3. Japanese Patent Unexamined Publication No., Hei 10-228969:

This publication discloses that a contact is complexly plated with hard particle and nickel.

The hard particle cut into tested portion so that good electrical contact is obtained. In view of this point, this publication is similar to the invention. However, since this publication does not provide function for suppressing relative sliding movement, an agglomerated solder is easily formed. Further, the solder film plated to tested portion is easily damaged.

4. Japanese Patent Unexamined Publication No., Hei 5-104856:

Description is given of this publication in the specification of the invention.

5. Japanese Patent Unexamined Publication No., Hei 4-34380:

Description is given of this publication in the specification of the invention.